

5. (Amended) The resin compound used for fabricating the interlayer dielectric of the printed wiring board as set forth in Claim 2, wherein the phenol novolak epoxy resin curing agent containing triazine rings within a molecule comprises one or two of melamine and benzoguanamine and a compound obtained from a condensation reaction with phenols and formaldehydes and has 5 to 25% by weight of nitrogen content.

6. (Amended) The resin compound used for fabricating the interlayer dielectric of the printed wiring board as set forth in Claim 2, wherein the maleimide compounds having thermosetting properties are any one or more of N,N'-(4,4-diphenylmethane)bismaleimide, bis(3-ethyl-5-methyl-4-maleimidephenyl)methane, 2,2-bis[4-(4-maleimidephenoxy)phenyl]propane, and thermosetting maleimide compounds obtained from Michael addition reaction of these maleimide compounds and polyamines.

7. (Amended) A method for producing the resin compound used for fabricating the interlayer dielectric of the printed wiring board as set forth in Claim 1, wherein a composition is made to have 20 to 70 parts by weight of epoxy resins, 5 to 30 parts by weight of polymers having crosslinkable functional groups within a molecule, 10 to 50 parts by weight of maleimide compounds having thermosetting properties, and a balance being a crosslinker added as necessary and a phenol novolak epoxy resin curing agent containing triazine rings within a molecule given that a total amount of the resin compound excluding a solvent is 100 parts by weight, and that a solids content

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cmo

after the composition is added to and dissolved in the solvent becomes 40 to 50% by weight.

9. (Amended) A resin sheet for forming an insulating layer used for manufacturing a copper-clad laminate, wherein the resin compound for fabricating the interlayer dielectric of the printed wiring board as set forth in Claim 1 is made into a sheet which is in a semi-cured state.

10. (Amended) A resin applied-copper foil constituted by forming a resin layer on a surface of copper foil employing the resin compound for fabricating the interlayer dielectric of the printed wiring board as set forth in Claim 1.

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